



Material Content Data Sheet



Sales Product Name	TLE7810G			Issued		28. August 2013		
MA#	MA001120008							
Package	PG-DSO-28-38			Weight*		830.79 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	14.636	1.76	1.76	17617	17617
leadframe	inorganic material	phosphorus	7723-14-0	0.071	0.01		86	
	non noble metal	zinc	7440-66-6	0.285	0.03		344	
	non noble metal	iron	7439-89-6	5.709	0.69		6871	
	non noble metal	copper	7440-50-8	231.798	27.90	28.63	279011	286312
wire	noble metal	gold	7440-57-5	1.008	0.12	0.12	1213	1213
encapsulation	organic material	carbon black	1333-86-4	1.134	0.14		1365	
	plastics	epoxy resin	-	52.161	6.28		62786	
	inorganic material	silicondioxide	60676-86-0	513.677	61.83	68.25	618303	682454
leadfinish	non noble metal	tin	7440-31-5	4.913	0.59	0.59	5914	5914
plating	noble metal	silver	7440-22-4	1.403	0.17	0.17	1689	1689
glue	plastics	epoxy resin	-	0.997	0.12		1200	
	noble metal	silver	7440-22-4	2.992	0.36	0.48	3601	4801
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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